

Electronic Patent Application Fee Transmittal

Application Number:	10611334			
Filing Date:	30-Jun-2003			
Title of Invention:	MEMS PACKAGING USING A NON-SILICON SUBSTRATE FOR ENCAPSULATION AND INTERCONNECTION			
First Named Inventor/Applicant Name:	John Heck			
Filer:	Kevin Reiff/cathy dikes			
Attorney Docket Number:	42P16325			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appt Issue fee	1501	1	1440	1440
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1740